



GENERAL

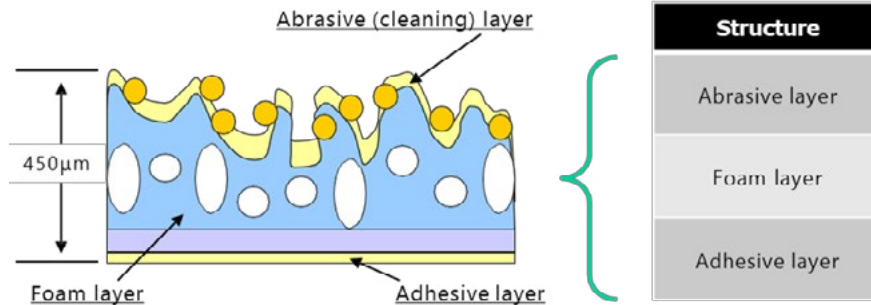
The presence of chlorine ions and chloride contamination on a bond pad surface can act as a catalyst for the copper (Cu) corrosion process and dramatically weaken the copper-aluminum (Cu-Al) intermetallic compounds (IMC). Reduced bond integrity can create long-term reliability issues for packaged devices.

LC6K (low-chlorine, abrasive foam) cleaning sheets were developed with chlorine levels of <100 ppm versus >1800ppm of the WA6000-SWE (green). The LC6K cleaning material has the same surface morphology / cross-section structure and matched material properties that define cleaning efficiency (i.e., hardness and wear rate). As with WA600-SWE, the maximum operating temperature of the LC6K material is T = 80C.

To reduce the risk of chlorine contamination the LC6K (Low-Cl) material can be used as a direct replacement for the chlorinated WA6000-SWE for probe card cleaning applications

Material Property	LC6K (Low-Cl)	WA6000 (Green)
Color	White / Blue	Green
Abrasive	#6000, Alumina	#6000, Alumina
Installed Thickness	~450um	~450um
Chlorine Content	< 100ppm	>1800ppm
Operating Temperature	OC to 80C	OC to 80C

CROSS SECTION



	Cleaning Material Configuration			
	Sheet	200mm Wafer	300mm Wafer	Custom Install
LC6K Layer Thickness	450 µm (nominal)	450 µm (nominal)	450 µm (nominal)	450 µm (nominal)
Support Carrier		725 ± 20µm (SEMI Standard)	775 ± 20µm (SEMI Standard)	Contact ITS
Total Installed Stack Height	450 ± 100µm	1175 ± 120µm	1225 ± 120 µm	Contact ITS

